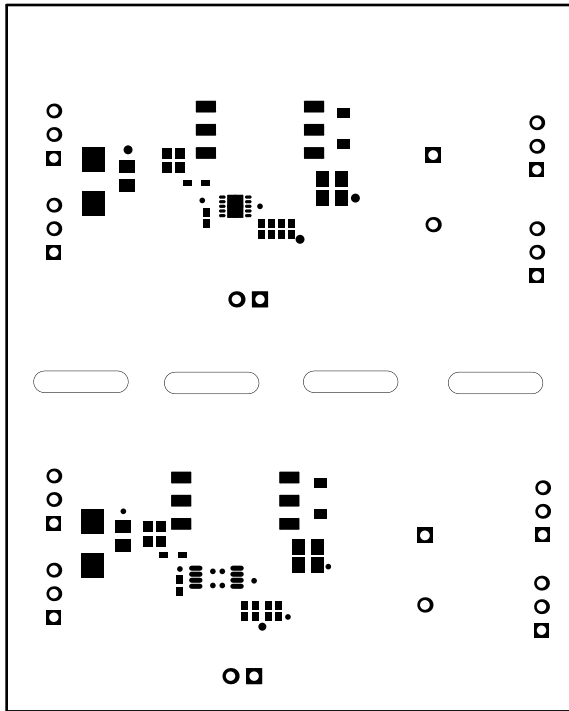
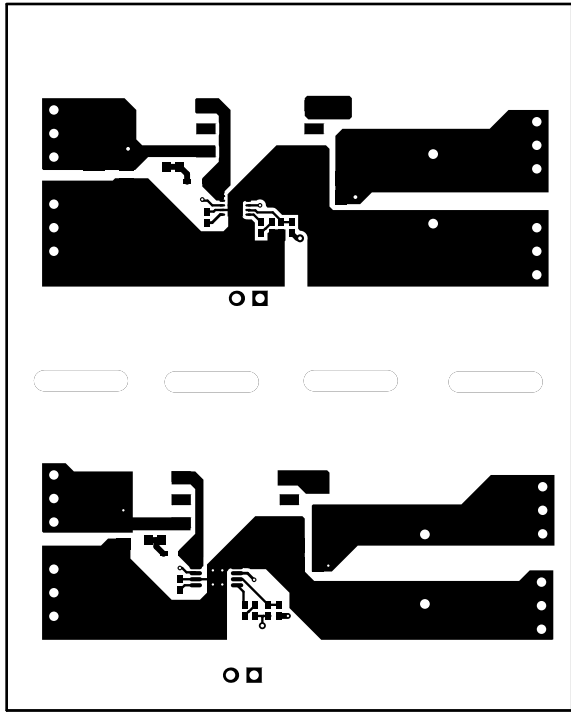


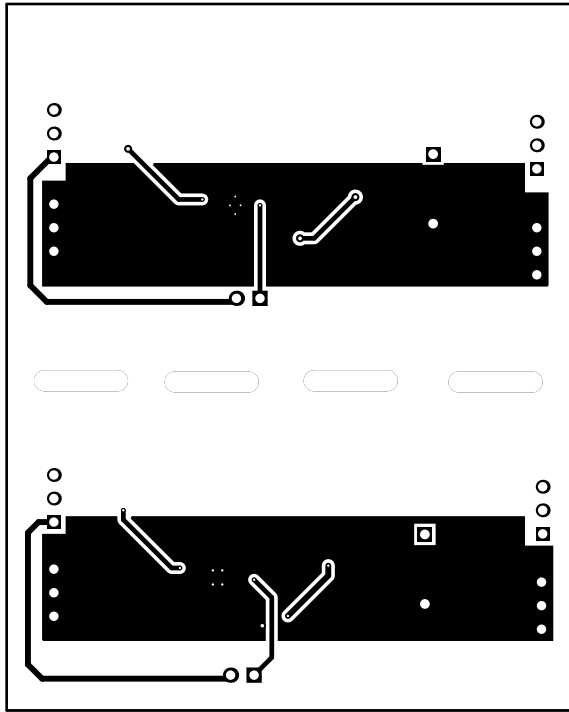
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDT003		
PLOT NAME = Top Overlay	GENERATED : 4/11/2018	9:45:12 AM	TEXAS INSTRUMENTS



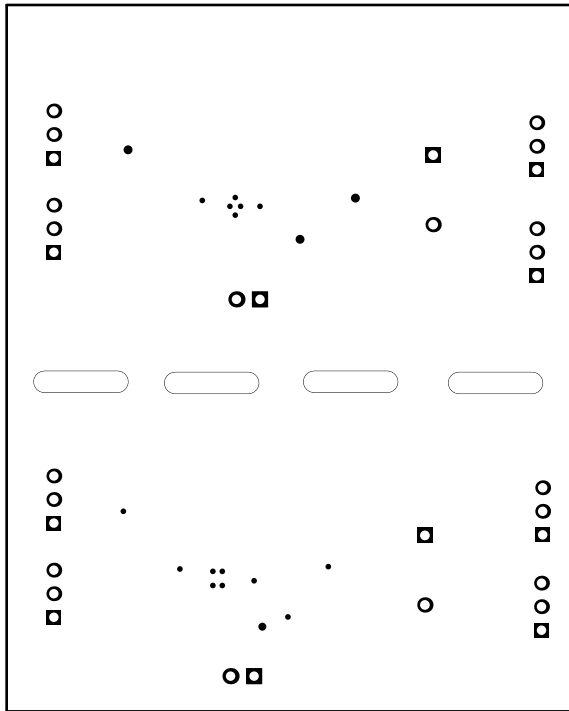
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDT003		
PLOT NAME = Top Solder Mask	GENERATED : 4/11/2018 9:45:14 AM	TEXAS INSTRUMENTS	



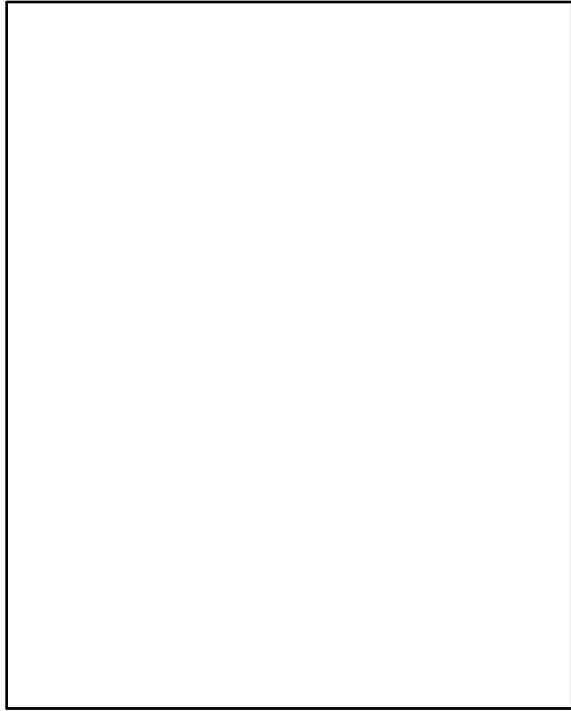
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDT003		
PLOT NAME = Top Layer	GENERATED : 4/11/2018 9:45:15 AM	TEXAS INSTRUMENTS	



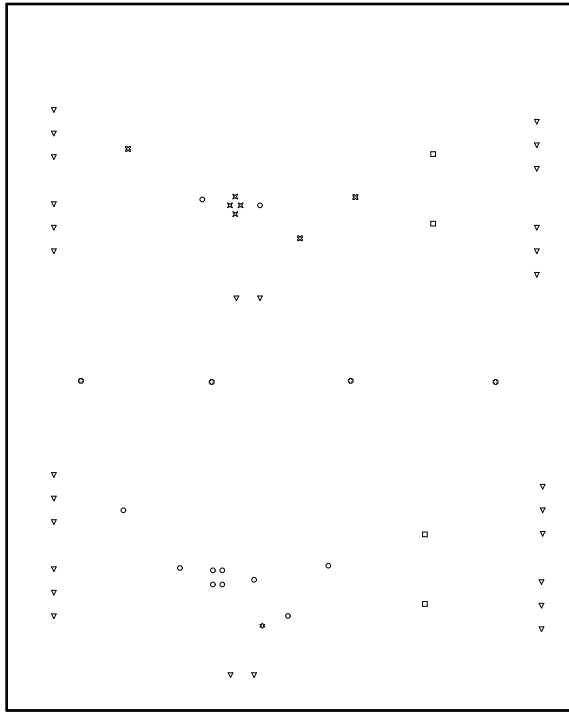
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDT003		
PLOT NAME = Bottom Layer	GENERATED : 4/11/2018 9:45:16 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDT003		
PLOT NAME = Bottom Solder Mask	GENERATED : 4/11/2018 9:45:18 AM	TEXAS INSTRUMENTS	



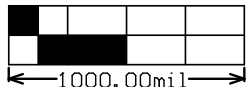
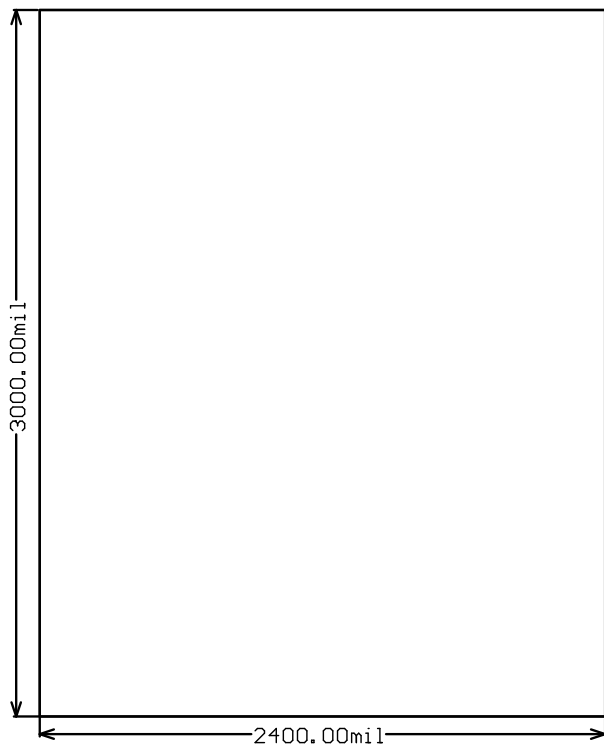
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDT003		
PLOT NAME = Bottom Overlay	GENERATED : 4/11/2018 9:45:19 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	4	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	11	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	1	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	3	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
▽	28	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	90.00mil (2.286mm)	PTH	Slot	Top Layer - Bottom Layer	
	55 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDT003		
PLOT NAME = Drill Drawing	GENERATED : 4/11/2018	9:45:20 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15044	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDT003		
PLOT NAME = Board Dimensions	GENERATED : 4/11/2018 9:45:22 AM	TEXAS INSTRUMENTS	

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